

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.02501	1.8	0.05184
	Doped Silicon	Silicon (Si)	7440-21-3	1.38921	100.0	2.88
		Subtotal		1.41422	101.8	2.93184
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.01296	100.0	2.1
		Subtotal		1.01296	100	2.1
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.05186	8.0	8.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.45704	8.8	9.24
	Filler	Silica fused	60676-86-0	42.03803	83.0	87.15
	Carbon Black	Carbon black	1333-86-4	0.1013	0.2	0.21
		Subtotal		50.64823	100	105
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01329	0.04	0.02756
	Copper alloy	Iron (Fe)	7439-89-6	0.03323	0.1	0.0689
	Copper alloy	Copper (Cu)	7440-50-8	33.18835	99.86	68.80354
		Subtotal		33.23487	100	68.9
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.06994	5.0	0.145
	Lead alloy	Silver (Ag)	7440-22-4	0.03497	2.5	0.0725
	Lead alloy	Lead (Pb)	7439-92-1	1.29394	92.5	2.6825
		Subtotal		1.39885	100	2.9
Clip Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00493	0.04	0.01021
	Copper alloy	Iron (Fe)	7439-89-6	0.01232	0.1	0.02553
	Copper alloy	Copper (Cu)	7440-50-8	12.29862	99.86	25.49655
		Subtotal		12.31587	100	25.53229
		Total		100.025	100	207.36413

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